



Special Issue on Research on Electroplating

Call for Papers

Electroplating is an application of a metal coating to a metallic or other conducting surface by an electrochemical reaction. Electroplating is both an art and a science. It based on several sciences and technologies which include physics, chemistry, metallurgy and so on. Electroplating is also retains some aspects of an art which can be learned only by experience.

There are many applications of electroplating, some of them become increasingly important at present, in which neither corrosion protection or decorative appeal is the reason for using a finish. The purpose of modify the surface properties by physical or chemical processes is to render materials suitable for the intended use. This special issue will be focused on studying different kinds of **research on electroplating** and their applications.

In this special issue, we intend to invite front-line researchers and authors to submit original research and review articles on exploring **research on electroplating**. Potential topics include, but are not limited to:

- Electroplating plastic
- Electroplating metal
- Plating surface finishing
- Electro plating
- Engineering and mechanical property
- Electroplating technology
- Electroplating application
- Three dimensional (3D) electrode
- Electroplating wastewater

Authors should read over the journal's [Authors' Guidelines](#) carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal's [Paper Submission System](#).

Please kindly notice that the “**Special Issue**” under your manuscript title is supposed to be specified and the research field “**Special Issue - Research on Electroplating**” should be chosen during your submission.

According to the following timetable:



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